

Advanced CMOS TTL Input – 74ACT00

Quad 2-Input NAND Gates with LSTTL compatible inputs in bare die form

Rev 1.0 18/05/21

Description

The 54ACT00 quad 2-input NAND gates is fabricated on a 1.5µm advanced CMOS process combining high speed LSTTL performance with CMOS low power. The device consists of x4 independent 2-input NAND gates performing the Boolean function $Y = \overline{A \cdot B}$ or $Y = \overline{A} + \overline{B}$. Internal circuitry comprises of three stages and includes buffered output for high noise immunity and stability. Inputs are directly compatible with LSTTL outputs. All inputs are protected against ESD and excess voltage transients.

Features:

- Inputs directly accept TTL
- Outputs directly interface CMOS, NMOS and TTL
- Outputs Source/Sink 24 mA
- Low Input Current: 1µA
- Functionally compatible with bipolar 74LS00
- Performance improvement versus 74HCT00
- Lower power alternative to bipolar logic.

Ordering Information

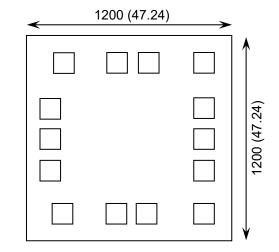
The following part suffixes apply:

No suffix - MIL-STD-883 /2010B Visual Inspection

For High Reliability versions of this product please see

<u>54ACT00</u>

Die Dimensions in µm (mils)



Supply Formats:

- Default Die in Waffle Pack (400 per tray capacity)
- Sawn Wafer on Tape On request
- Unsawn Wafer On request
- Die Thickness <> 350µm(14 Mils) On request
- Assembled into Ceramic Package On request

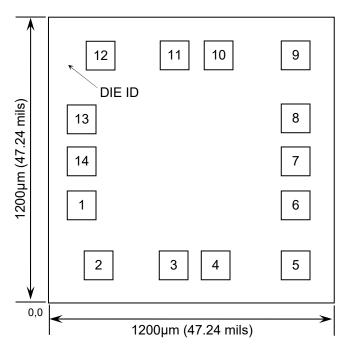
Mechanical Specification

Die Size (Unsawn)	1200 x 1200 47 x 47	µm mils	
Minimum Bond Pad Size	120 x 120 4.72 x 4.72	µm mils	
Die Thickness	350 (±20) 13.78 (±0.79)	µm mils	
Top Metal Composition	Al 1%Si 1.1µ	m	
Back Metal Composition	N/A – Bare Si		





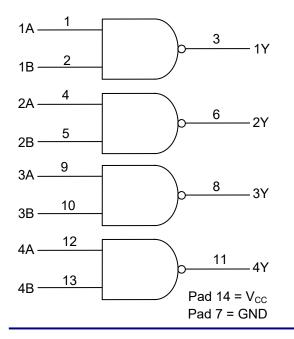
Pad Layout and Functions



PAD	FUNCTION	COORDIN	ATES (µm)					
FAD	FUNCTION	X	Y					
1	1A	100	350					
2	1B	150	100					
3	1Y	480	100					
4	2A	660	100					
5	2B	990	100					
6	2Y	990	350					
7	GND	990	540					
8	3Y	990	720					
9	3A	990	980					
10	3B	660	980					
11	4Y	480	980					
12	4A	150	980					
13	4B	100	720					
14	V _{cc}	100	540					
CON	CONNECT CHIP BACK TO V _{cc} OR FLOAT							

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Logic Diagram



Function Table

INP	OUTPUT					
А	В	Y				
L	L	Н				
L	Н	H				
Н	L	Н				
Н	Н	L				
H = High level (steady state) L = Low level (steady state)						







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Absolute Maximum Ratings¹

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PARAMETER	SYMBOL	VALUE	UNIT				
DC Supply Voltage (Referenced to GND)	V _{CC}	-0.5 to +7.0	V				
DC Input Voltage (Referenced to GND)	V _{IN}	-0.5 to V _{CC} +0.5	V				
DC Output Voltage (Referenced to GND)	V _{OUT}	-0.5 to V _{CC} +0.5	V				
DC Input Current	I _{IN}	±20	mA				
DC Output Current, per pad	I _{OUT}	±50	mA				
DC Supply Current, V_{CC} or GND, per pad	I _{CC}	±50	mA				
Power Dissipation in Still Air ²	PD	750	mW				
Storage Temperature Range	T _{STG}	-65 to 150	°C				

1. Operation above the absolute maximum rating may cause device failure. Operation at the absolute maximum ratings, for extended periods, may reduce device reliability. 2. Measured in plastic DIP package, results in die form are dependent on die attach and assembly method.

Recommended Operating Conditions³ (Voltages Referenced to GND)

	1 0				-
PARAMETE	R	SYMBOL	MIN	MAX	UNITS
DC Supply Voltage		V _{CC}	4.5	5.5	V
DC Input or Output Voltag	е	V _{IN} ,V _{OUT}	0	V _{cc}	V
Operating Temperature R	ange	TJ	-55	+125	°C
Output current - High	I _{ОН}	-	-24	mA	
Output current - Low	I _{OL}	-	24	mA	
Input Rise or Fall rate	$V_{CC} = 4.5V$	Δt/ΔV	0	10	ns/V
(V_{IN} from 0.8V to 2V)	$V_{CC} = 5.5V$	ΔυΔν	0	8	113/ V

3. This device contains protection circuitry to guard against damage due to high static voltages or electric fields. However, precautions must be taken to avoid applications of any voltage higher than maximum rated voltages to this high-impedance circuit. For proper operation, V_{IN} and V_{OUT} should be constrained to the range GND \leq (V_{IN} or V_{OUT}) \leq V_{CC} . Unused inputs must always be tied to an appropriate logic voltage level (e.g., either GND or V_{CC}). Unused outputs must be left open.

DC Electrical Characteristics (Voltages referenced to GND)

PARAMETER	SYMBOL	V _{cc}	CONDITIONS	LIMITS			UNITS
	OTHEOL	•00	CONDITIONO	25°C	85°C	FULL RANGE ⁴	
Minimum High-Level	el V _{IH}	4.5V	V _{OUT} = 0.1V	2	2	2	V
Input Voltage	VIH	5.5V	or V_{CC} -0.1V	2	2	2	v
Maximum Low-Level		4.5V	V _{OUT} = 0.1V	0.8	0.8	0.8	V
Input Voltage		5.5V	or V_{CC} -0.1V	0.8	0.8	0.8	v
		4.5V	Ι _{ουτ} = 50μΑ	0.1	0.1	0.1	V
		5.5V	1001 0007	0.1	0.1	0.1	
Minimum Low-Level	V _{OL}	4.5V	$V_{IN} = V_{IL} \text{ or } V_{IH}^{5}$	0.36	0.44	0.50	V
Output Voltage	V OL	5.5V	I _{OL} = 24mA	0.36	0.44	0.50	, v
		4.5V	$V_{IN} = V_{IL} \text{ or } V_{IH}^{5,6}$	-	-	1.65	V
		5.5V	$I_{OL} = 50 \text{mA}$	-	-	1.65	

4. $-55^{\circ}C \le T_{J} \le +125^{\circ}C$ 5. All outputs loaded; thresholds on input associated with output under test. 6. Test time 1sec max, measurement made by forcing indicated current and measuring voltage to minimize power dissipation. Test verifies a minimum 75 Ω transmission-line drive capability at 125°C





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DC Electrical Characteristics Continued (Voltages referenced to GND)

			•	•		,	
PARAMETER	SYMBOL	V _{cc}	CONDITIONS	LIMITS		TS	UNITS
	STINDOL	♥ CC	CONDITIONS	25°C	85°C	FULL RANGE ⁴	
		4.5V	Ι _{ουτ} = 50μΑ	4.4	4.4	4.4	V
Minimum High-Level	V _{OH}	5.5V	ι _{ουτ} – 30μΑ	5.4	5.4	5.4	v
Output Voltage	V OH	4.5V	$V_{IN} = V_{IL} \text{ or } V_{IH}^{5}$	3.86	3.76	3.7	V
		5.5V	I _{ОН} = -24mA	4.86	4.76	4.7	v
Maximum Input Leakage Current	I _{IN}	5.5V	$V_{IN} = V_{CC}$ or GND	±0.1	±1.0	±1.0	μA
Additional Maximum I _{CC} / Input	ΔI _{CCT}	5.5V	$V_{IN} = V_{CC} - 2.1V$	0.6	1.5	1.6	mA
Minimum Dynamic	I _{OLD}	5.5V	V _{OLD} = 1.65V Max	-	75	50	mA
Output Current ⁷	I _{OHD}	5.5V	V _{OHD} = 3.85V Min	-	-75	-50	
Maximum Quiescent Supply Leakage Current	I _{CC}	5.5V	$V_{IN} = V_{CC} \text{ or GND}$ $I_{OUT} = 0\mu A$	4	40	80	μA

7. Maximum test duration 2ms, one output loaded at a time.

AC Electrical Characteristics⁸ $v_{cc} = 5.0V \pm 0.5V$

PARAMETER	SYMBOL	Vac			S	UNITS	
	OTHEOL	• 00		25°C	85°C	FULL RANGE ⁴	
Maximum Propagation Delay	t _{PLH}	5.0V	C _L = 50pF, Input	9.0	9.5	10.8	ns
Input A to Output Y (Figure 1)	t _{PHL}	5.0V		7.0	8.0	13.2	113
Maximum Input	C _{IN}	5.0V	T. = 25°C		TYPIC	AL	pF
Capacitance			1, 200		4.5		P
Power Dissipation Capacitance	C _{PD}	5.0V	$T_{J} = 25^{\circ}C,$ $C_{L} = 50pF$		30		pF

8. Not production tested in die form, characterized by chip design





Switching Waveform

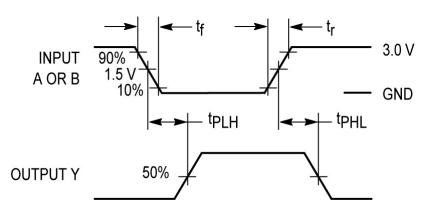
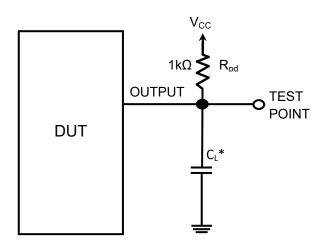


Figure 1 – Propagation delay, Input A or B to Output Y

Test Circuit



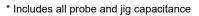


Figure 2 - Test Circuit

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